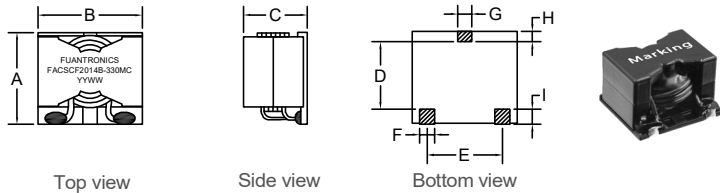


P/N: FACSCF2014B-330MC

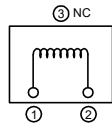


Outline Dimensions(Unit:mm)

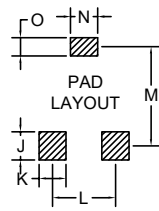


A	B	C	D	E	F	G	H	I
±0.50	±0.50	Max	±0.50	±0.50	REF	REF	REF	REF
18.5	21.0	14.5	13.8	14.3	2.50	2.50	1.65	2.70

Electrical Schematic



Suggested Pad layout



J	5.00 REF
K	4.50 REF
L	14.3 REF
M	16.0 REF
N	4.50 REF
O	3.60 REF

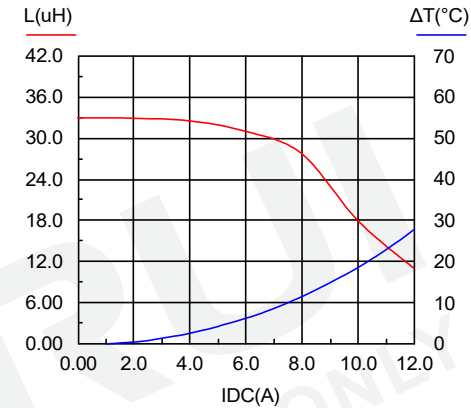
- ***Assemblage design, sturdy structure.
- ***High inductance, high current, low magnetic loss.
- ***low ESR, small parasitic capacitance.
- ***Temperature rise current and saturation current is less influenced by environment.

Electrical Characteristics(@25°C)

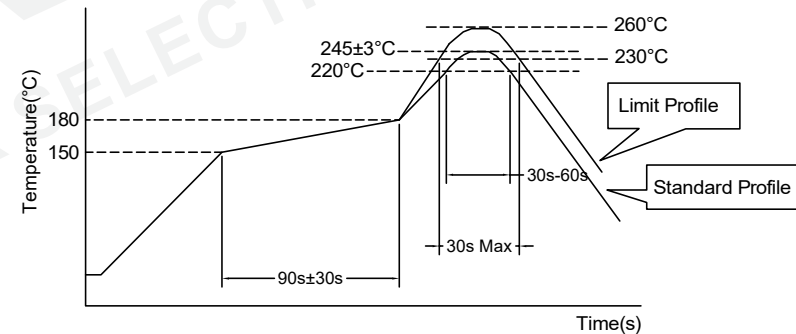
Inductance 100KHz,0.1V	DC Resistor	Saturated current 7.3A	Temperature rise current 14A
33.0uH±20%	13.3mΩ Max	L(7.3A)=80%*L0A Typ	T≤40°C Typ

- ***Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.
- ***Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).
- ***Operating Temperature: -40°C~+125°C.
(Temperature rise included)
- ***Storage Temperature: -40°C~+125°C.
- ***Storage Humidity:RH10%~70%.

Saturation current VS temperature rise current curve:



Recommended Soldering Temperature Graph.



	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times